



**EXPEDITED PROCEDURE - EXAMINING GROUP 2812**

6/B (KLEZ)  
J. Steptae  
1/9/01  
**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Paul A. Farrar Examiner: Ron Pompey  
Serial No.: 09/253,611 Group Art Unit: 2812  
Filed: February 19, 1999 Docket: 303.572US1  
Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

**AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116**

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

In response to the final Office Action mailed September 26, 2000, please amend the application as follows:

**IN THE CLAIMS**

Claims 1, 9, 12, 13 and 16 are amended hereinbelow. In addition, new claims 64-67 are added. As a result, claims 1-23 and 64-67 are pending.

Please amend claims 1, 9, 12, 13 and 16 as follows:

- Sub 27  
B1
1. (Twice Amended) A method of forming a solder ball contact, comprising:  
forming a metal contact pad on a substrate;  
forming an insulating layer on the metal contact pad;  
removing a portion of the insulating layer to expose a portion of the metal contact pad,  
thereby forming an exposed portion of the metal contact pad, the exposed portion having a  
predetermined diameter;  
immersing the substrate in molten solder;  
depositing solder on the exposed portion of the metal contact pad using selective  
deposition, thereby forming a solder contact; and  
annealing the solder contact to form a solder ball contact having a diameter in a range of  
about 2.5 microns to no greater than 100 microns.

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